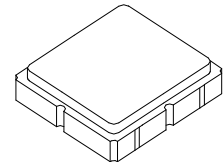


- RF SAW Filter, 2330 MHz, 60 MHz BW
- 3.0 x 3.0 x 1.4 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)



**SF2160E**

**2330 MHz  
SAW Filter**



**SM3030-6**

**Absolute Maximum Ratings**

Rating	Value	Units
Input Power	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Component Storage Temperature Range	-50 to +95	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_c$			2330		MHz
Insertion Loss 2300 to 2360 MHz	IL			2.4	3.2	dB
Amplitude Ripple:						
2300 to 2360 MHz				1.1	2	dB
2300 to 2320 MHz				0.3	1	
2320 to 2340 MHz				0.6	1	
2340 to 2360 MHz				0.5	1	
Return Loss 2300 to 2360 MHz			9	9.5		dB
Attenuation Referenced to 0 dB:						
DC to 2085 MHz			25	30		dB
2097 to 2235 MHz			25	36		
2235 to 2256 MHz			15	29		
Case Style			SM3030-6 3 x 3 x 1.4 mm Surface-Mount			
Lid Symbolization, Y=year, WW=week, S=shift, See note 4			826 // YWWS			

**Electrical Connections**

Connection	Terminals
Input	2
Output	5
Ground	All others

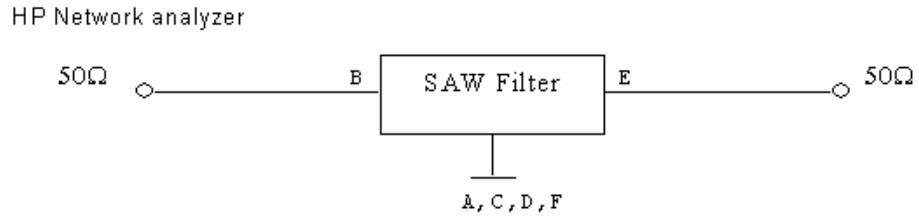


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

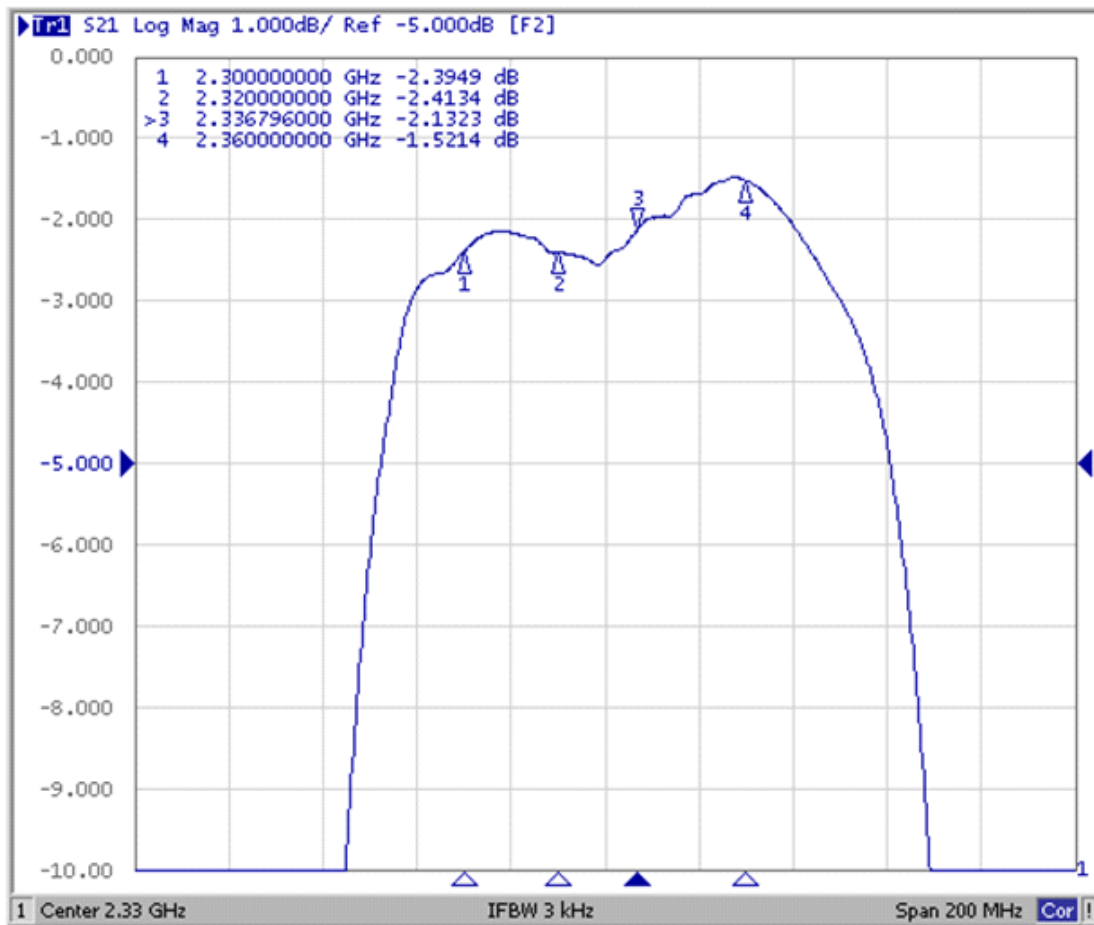
**NOTES:**

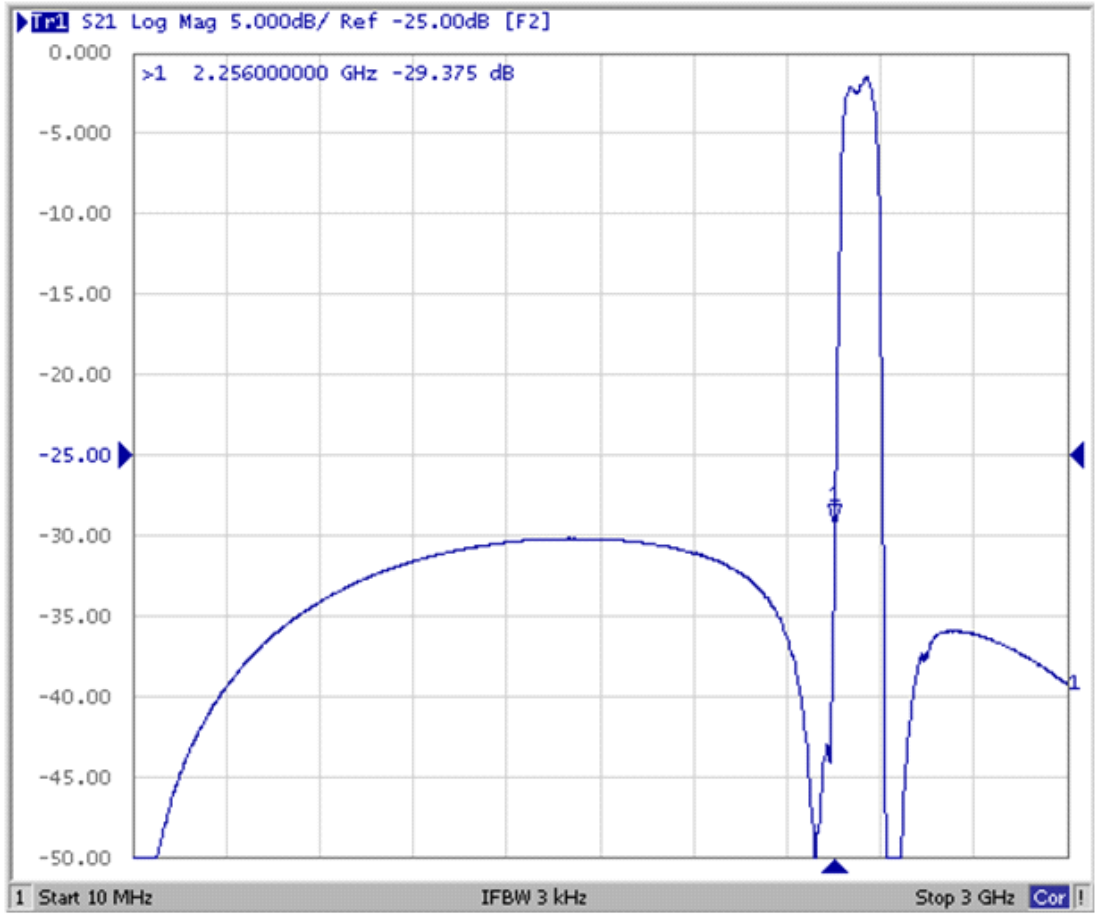
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency,  $f_c$ .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.

## Testing Environment

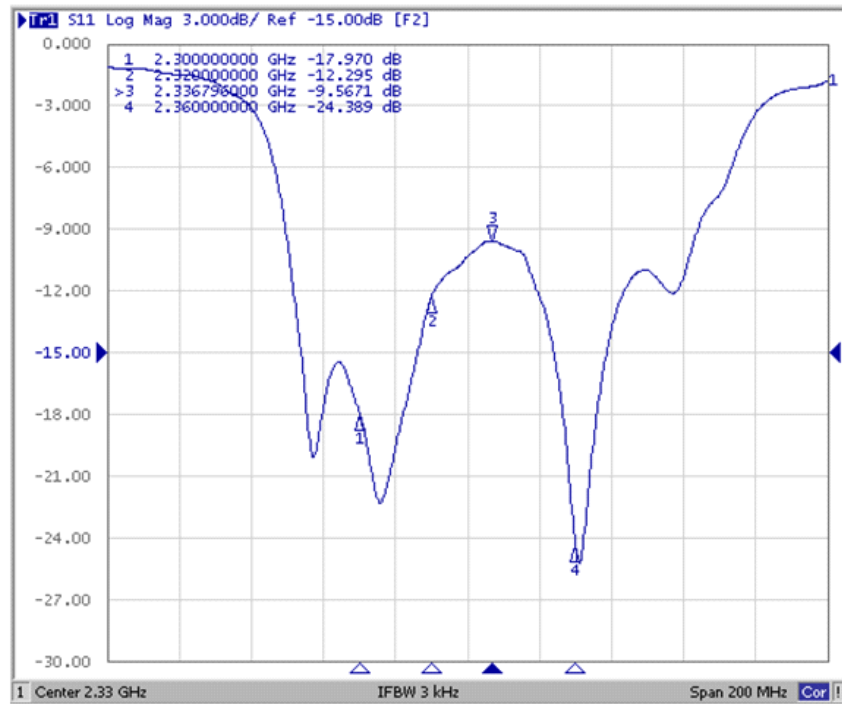


## Frequency Response

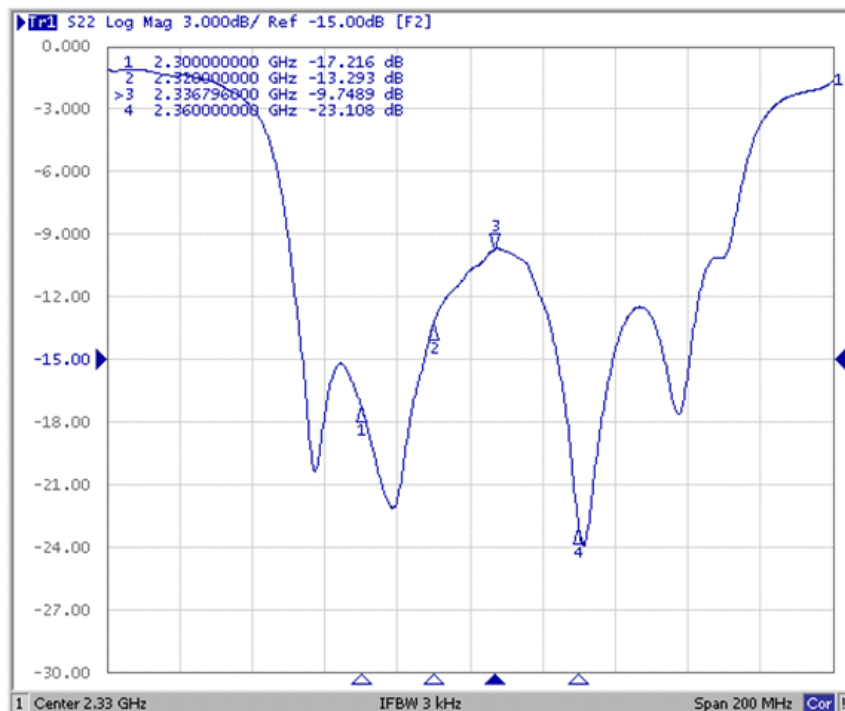




## S11

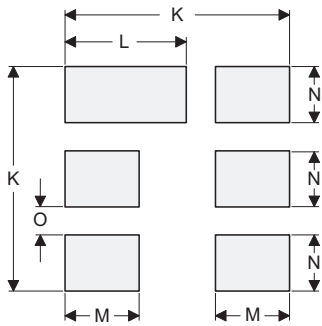
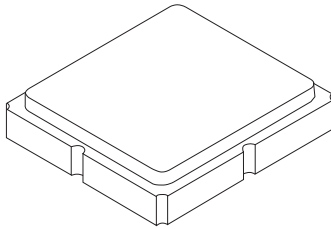


## S22



# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

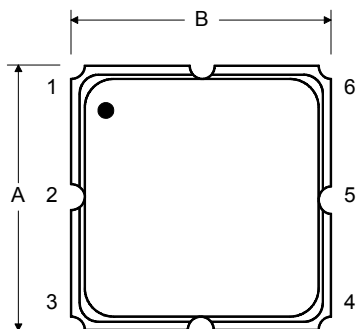
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

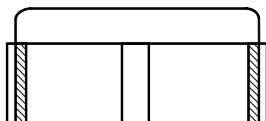
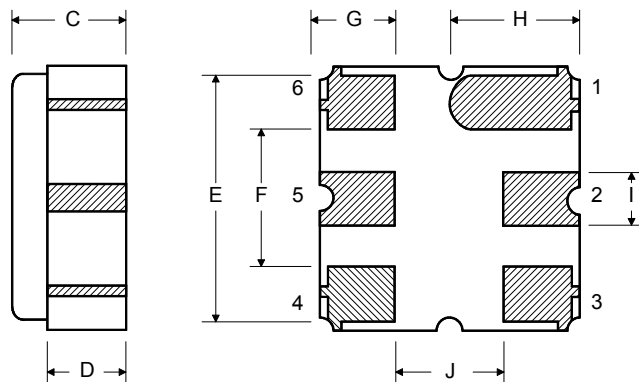
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic
Pb Free	

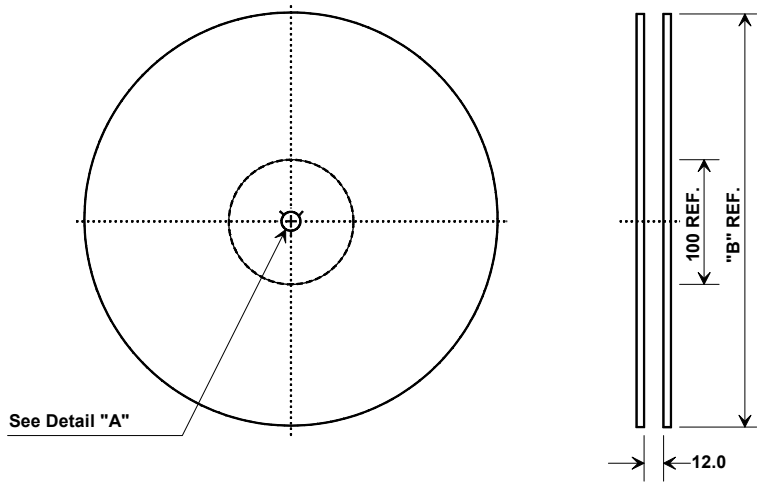
### TOP VIEW



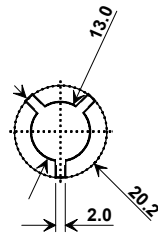
### BOTTOM VIEW



## Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



## COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm

